

4 recognizing a target structure in the mask set data; and
5 configuring the recipe parameters responsive to the recognized target structure, before
6 an exemplar of the mask set data is created.

1 2. (Unamended) The method of claim 1 wherein the recipe parameters for a process
2 layer are queried from a database.

1 3. (Unamended) The method of claim 1 wherein the recipe parameters comprise at least
2 one of wafer processing parameters, inspection parameters, and control parameters.

1 4. (Unamended) The method of claim 1 wherein the target structure comprises at least
2 one of alignment site, measurement site, overlay target, and array element.

1 5. (Amended) For an instrument instructed by a recipe to perform a task on a wafer, a
2 method comprising:

3 receiving design data describing a die;

4 extracting parameters from the design data relevant to the configuration of the

5 instrument, before an exemplar of the design data is created;

6 applying the extracted parameters to at least one die on the wafer; and

7 creating the recipe from the applied extracted parameters, the recipe for performing
8 the task.

1 6. (Unamended) The method of claim 5 wherein the task includes at least one of
2 inspection and metrology.

1 7. (Unamended) The method of claim 5 wherein the applying uses a stepper setup file.

1 8. (Unamended) The method of claim 5 wherein the design data includes at least one of
2 element names and instance types.

1 9. (Unamended) The method of claim 5 further comprising inspecting the wafer using
2 the recipe.

1 10. (Unamended) The method of claim 9 wherein the inspecting is micro inspection.

1 11. (Unamended) The method of claim 9 wherein the inspecting is macro inspection.

1 12. (Unamended) The method of claim 9 wherein the inspecting is darkfield inspection.

1 13. (Unamended) The method of claim 5 further comprising measuring the wafer using
2 the recipe.

1 14. (Unamended) The method of claim 13 wherein the measuring is film measurement.

1 15. (Unamended) The method of claim 13 wherein the measuring is critical dimension
2 measurement.

1 16. (Unamended) The method of claim 13 wherein the measuring is overlay
2 measurement.

17. (Amended) A recipe extraction system using design data specifying one or more die, the system comprising:

an access module to access the design data;

an analyzer to extract parameters from the design data; and

a configuration module to produce a recipe for controlling one of an inspection and a

metrology instrument, before an exemplar of the design set data is created.

18. (Unamended) The system of claim 17 wherein the access module is a network interface.

19. (Unamended) The system of claim 17 wherein the analyzer performs overlay recipe extraction.

20. (Unamended) The system of claim 17 wherein the analyzer performs inspection recipe extraction.

21. (Unamended) The system of claim 17 wherein the recipe is a set of instructions for measuring a wafer.

22. (Unamended) The system of claim 17 wherein the recipe is a set of instructions for inspecting a wafer.

23. (Amended) An inspection/metrology instrument using design data specifying one or more die, the instrument comprising:

an input interface for accessing the design data;

an analyzer to recognize target structures in the design data; and

a recipe module creating a recipe, before an exemplar of the design set data is created, in

accordance with the recognized target structures.